New Product Introduction

July 2024

XHP™ 2 CoolSiC™ MOSFET 3.3 kV with .XT

EiceDRIVER™ 2ED314xMC12L (2ED-X3 Compact)

HybridPACK™ Drive G2

CoolMOS™ S7T and S7TA SJ MOSFET with integrated temperature sensor for industrial and automotive applications

OptiMOS™ 7 power MOSFET 40 V in SuperSO8

CoolSiC™ MOSFET 750 V G1 in QDPAK TSC and D2PAK-7 package industrial and automotive graded

6500 V, 1000 A single switch IGBT module FZ1000R65KE4

CAN FD 5MB Family TLE935*B*

AIROC™ CYW43022 Wi-Fi 5 + Bluetooth® 5.4 combo – an ultra-low-power solution for IoT applications needing long battery life

Application kit APPKIT_A2G_SAFETY

Evaluation kit EVAL_PMG1_S1_DRP

Evaluation boards for Infineon 8-pin Solid State Isolators

PSoC™ Automotive CY3290-CYAT8168X Multitouch 6XL evaluation kit

TRAVEO™ T2G Cluster 4M Lite Kit

XHP™ 2 CoolSiC™ MOSFET 3.3 kV with .XT

Decarbonize transportation thanks to XHP™ 2 CoolSiC™ MOSFET 3.3 kV with .XT. Its unparalleled performance is enabled by the unique combination of CoolSiC™ MOSFET 3.3 kV with integrated body diode, XHP™ 2 housing and .XT interconnection technology.

Features

- High Fsw
- Compact size
- Low losses
- Highest I nom
- .XT joining technology
- I2t surge current robustness

Benefits

- Energy efficiency
- High power density
- Enhanced lifetime

Competitive advantage

- Unique combination of highest power density, energy efficiency and ruggedness

Target applications

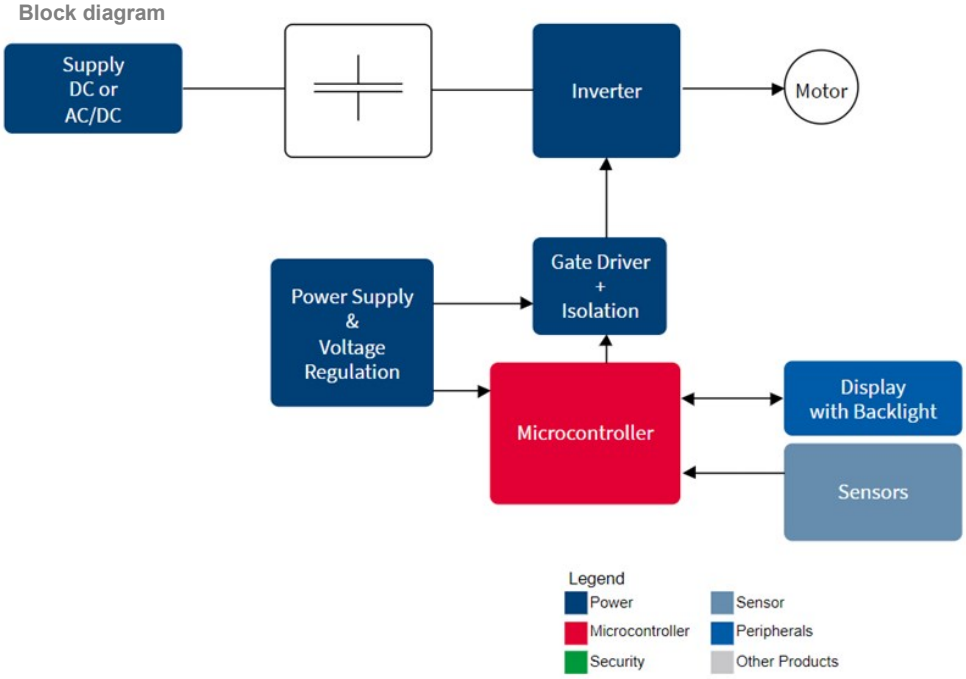
- Rail transportation: traction converters
- Renewables: PV, ESS, H2 electrolysis

Product collaterals / Online support

Product page: FF2000UXTR33T2M1

Product page: FF2600UXTR33T2M1

Block diagram



Product overview incl. data sheet link

OPN	SP Number	Package
FF2000UXTR33T2M1BPSA1	SP005400736	AG-XHP2K33-3031
FF2600UXTR33T2M1BPSA1	SP005404848	AG-XHP2K33-3031

EiceDRIVER™ 2ED314xMC12L (2ED-X3 Compact)

The EiceDRIVER™ 2ED314xMC12L is a family of dual-channel isolated gate driver ICs, designed to drive Si MOSFETs, IGBTs and SiC MOSFETs. All products are available in a 14-pin DSO package with 8 mm input-to-output creepage and provide reinforced isolation. All variants offer dead-time control (DTC) functionality and independent channel operation. This allows the operation as dual-channel low-side driver, dual-channel high-side driver or half-bridge gate driver with a configurable dead-time.

Features

- For use with 600 V / 650 V / 1200 V / 1700 V / 2300 V IGBTs, Si and SiC MOSFETs
- Up to 6.5 A typical peak output current
- 35 V absolute maximum output supply voltage
- Active shutdown and short circuit clamping
- 3.3 V and 5 V input supply voltage
- Galvanically isolated coreless transformer gate driver with 8 mm input-to-output and 3.3 mm channel-to-channel creepage and clearance

Benefits

- Well suited for fast-switching applications with 39 ns propagation delay with 5 ns channel-to-channel delay mismatch (skew) and high common-mode transient immunity CMTI > 200 kV/µs
- Safety certification - UL 1577 (File 311313), reinforced insulation according to IEC 60747-17 (planned)

Target applications

- EV charging
- Energy storage and UPS systems
- Solar inverters
- Server and telecom switched mode power supplies (SMPS)
- AC and brushless DC motor drives

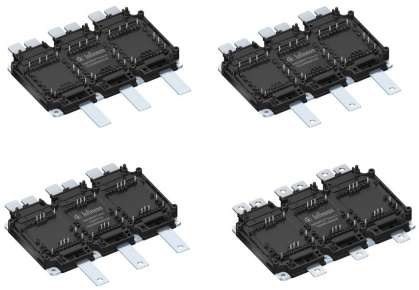
Product collaterals / Online support

Product family page

Product overview incl. datasheet link

OPN	SP Number	Package
2ED3140MC12LXUMA1	SP005909927	PG-DSO-14
2ED3141MC12LXUMA1	SP005909929	PG-DSO-14
2ED3142MC12LXUMA1	SP005916552	PG-DSO-14
2ED3143MC12LXUMA1	SP005916554	PG-DSO-14
2ED3144MC12LXUMA1	SP005916556	PG-DSO-14
2ED3145MC12LXUMA1	SP005916558	PG-DSO-14
2ED3146MC12LXUMA1	SP005916560	PG-DSO-14
2ED3147MC12LXUMA1	SP005916562	PG-DSO-14

HybridPACK™ Drive G2



The HybridPACK™ Drive G2 is a compact B6-bridge power module optimized for traction inverter applications, offering scalability up to 300 kW within the 750 V and 1200 V class.

The product is available with different current ratings, voltage levels and Infineon's next generation chip technologies EDT3 (Si IGBT) and CoolSiC™ G2 MOSFET. HybridPACK™ Drive G2 additionally provides new features for optimal system cost, such as an integration option for next-generation phase current sensor.

Features

- Low switching losses
- Low inductive design
- Short-time extended operation temperature
- High creepage and clearance distances
- Direct-cooled PinFin base plate
- Die attach technology with sintering
- Improved pin rivet ensuring high robustness over entire temperature range

Benefits

- Higher temperature cycling capability
- Integrated diode temperature sensors
- New plastic material for better temperature capability
- New frame design for lower system BOM
- Lower AC contact resistance and tab temperature

Competitive advantage

- Enable scalable inverter platform development
- Superior gate oxide and cosmic ray reliability
- Improved thermal conductivity
- High robustness over entire temperature range
- Increased durability especially in harsh environment

Product collaterals / Online support

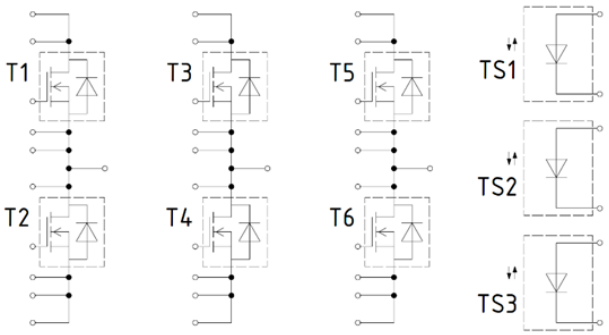
Product family page

Target applications

- Automotive traction inverter
- CAV traction inverter

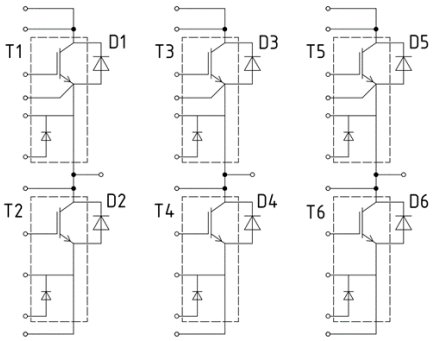
Block diagram

FS01MR08A8MA2LBC and FS02MR12A8MA2B



Block diagram

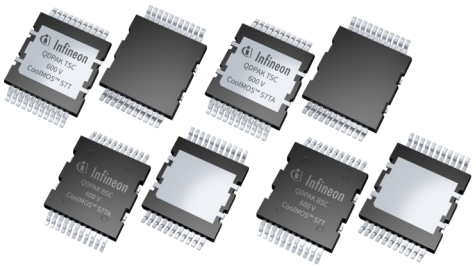
FS1150R08A8P3x



Product overview incl. datasheet link

OPN	SP Number	Package
FS1150R08A8P3LBCHPSA1	SP005724696	AG-HDG2XT-7661
FS1150R08A8P3LMCHPSA1	SP005908114	AG-HDG2XT-7661
FS01MR08A8MA2LBCHPSA1	SP005567339	AG-HDSICXT-1
FS02MR12A8MA2BBPSA1	SP005588581	AG-HDSICXT-1

CoolMOS™ S7T and S7TA SJ MOSFET with integrated temperature sensor for industrial and automotive applications



The CoolMOS™ S7T and S7TA with embedded temperature sensor increases junction temperature sensing accuracy and robustness while enabling easy implementation and functional safety. The device is optimized for low-frequency and high-current switching applications. It is an ideal fit for industrial application such as solid-state relay, circuit breaker designs and line rectification in SMPS as well as automotive applications like battery disconnect, eFuses. and on-board charger.

The temperature sensor enhances CoolMOS™ S7 features, allowing the best possible utilization of the power transistor.

Features

- Optimized price performance
- Tailored for low-frequency switching
- Reduced parasitic source inductance
- Seamless diagnostics
- Accurate and fast monitoring over time
- High current capability
- Enhanced protection
- Optimized thermal device utilization
- Cutting-edge top-side-cooled package

Benefits

- Minimized conduction losses
- Increased system performances
- Allowing more compact design over EMR
- Lower TCO over prolonged time
- Enabling higher power density designs
- Reduction of external sensing elements
- Best utilization of power transistor
- 40% more accurate than discrete sensor
- 4x faster than discrete sensor solution
- Optimal PCB space utilization
- Enabling functional safety
- Best in class thermal dissipation

Target applications

- Solid State Relay (SSR)
- Solid State Circuit Breaker (SSCB)
- Motor soft starter
- Power distribution unit (AC-DC)
- eFuse
- On-board charger
- Battery disconnection

Product collaterals / Online support

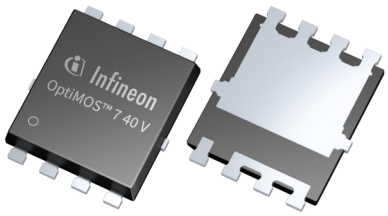
Product family page 600 V CoolMOS™ S7 / S7T

Product family page 600V CoolMOS™ S7A

Product overview incl. datasheet link

OPN	SP Number	Package
IPDQ60T017S7XTMA1	SP005737951	PG-HDSOP-22
IPDQ60T022S7XTMA1	SP005737954	PG-HDSOP-22
IPQC60T017S7XTMA1	SP005737963	PG-HDSOP-22
IPQC60T022S7XTMA1	SP005737968	PG-HDSOP-22
IPDQ60T017S7AXTMA1	SP005737985	PG-HDSOP-22
IPDQ60T022S7AXTMA1	SP005737990	PG-HDSOP-22
IPDQ60T040S7AXTMA1	SP005737999	PG-HDSOP-22
IPQC60T017S7AXTMA1	SP005738009	PG-HDSOP-22
IPQC60T022S7AXTMA1	SP005738012	PG-HDSOP-22
IPQC60T040S7AXTMA1	SP005738015	PG-HDSOP-22

OptiMOS™ 7 power MOSFET 40 V in SuperSO8



Infineon introduces the best-in-class 40 V power MOSFET in the latest OptiMOS™ 7 trench technology. Maintaining the technology leadership position, this new product expands the OptiMOS™ 7 portfolio from the industry´s first 15 V power MOSFETs to the lowest $R_{DS(on)}$ in a SuperSO8 40 V power MOSFET, minimizing the system's energy loss and making it best suited for BMS applications.

Compared to the existing OptiMOS™ 6 40 V products, the $R_{DS(on)}$ is improved by 40%. In addition, the SuperSO8 package makes a 50% PCB real estate area reduction possible compared to the DirectFET™ (L) solution while making the need for parallelization obsolete.

The new OptiMOS™ 7 power MOSFET 40 V offers a leap forward in $R_{DS(on)}$ reduction, a highly beneficial product feature for BMS applications. It facilitates increased power density, improved system efficiency and system cost reduction.

Features

- BiC 40 V power MOSFET in SuperSO8
- Outstanding $R_{DS(on)}$
- Industry standard footprint
- Wide safe operating area

Benefits

- Best fit in BMS applications
- Energy loss minimization with highest power density
- Multiple sourcing possibility
- Increased reliability and robustness

Target applications

- BMS
- SMPS

Product collaterals / Online support

Product page

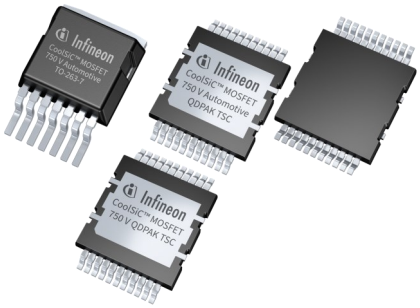
Competitive advantage

- BiC 40 V power MOSFET in a SuperSO8 in the market
- Outstanding $R_{DS(ON)}$
- Industry standard footprint
- High system efficiency and performance
- System form factor reduction for highest power density
- Reduced system cost
- Increased reliability and robustness
- Wide safe operating area

Product overview incl. datasheet link

OPN	SP Number	Package
ISCH42N04LM7ATMA1	SP005975805	PG-TDSON-8

CoolSiC™ MOSFET 750 V G1 in QDPAK TSC and D2PAK-7 package industrial and automotive graded



The new CoolSiC™ MOSFET 750 V G1 in QDPAK top-side cooling (TSC) and D2PAK-7 package is a highly robust SiC MOSFET for the best system performance and reliability. The CoolSiC™ MOSFET 750 V leverages more than 20 years of SiC experience in Infineon. It offers an edge in performance, reliability, and robustness, with gate driving flexibility, enabling the simplified and cost-effective system design for top efficiency and power density. The innovative top-side-cooling package further enhance the CoolSiC™ 750 V strengths, offering more density, optimized power loop design and less system and assembly cost.

Features

- Highly robust 750 V technology
- Best-in-class $R_{DS(on)}$ x Q_{fr}
- Excellent R_{on} x Q_{oss} and R_{on} x Q_G
- Low C_{rss}/C_{iss} together and high V_{gsth}
- 100% avalanche tested
- .XT interconnection technology for best-in-class thermal performance

Benefits

- Superior efficiency in hard switching
- Enables higher switching frequency
- Higher reliability
- Withstand bus voltages beyond 500 V
- Robustness against parasitic turn
- Unipolar driving

Target applications

- Industrial
  - Solid-state relay (SSR)
  - 1-phase string inverter solutions
  - AC-DC power conversion for telecom infrastructure
  - Energy storage systems
  - EV charging
  - Server power supplies
- Automotive
  - Onboard battery charger for electric vehicles
  - High-voltage DC-DC converter for electric vehicles

Competitive advantage

- The CoolSiC™ MOSFET 750 V is the most balanced technology combining ease-of-use, switching efficiency and superior thermal performances
  - Enhanced robustness to withstand bus voltages beyond 500 V
  - Best-in-class figures of merit
  - Unique diffusion soldering technique
  - Ultra-low R_{on}

Product collaterals / Online support

Product family page

Product overview incl. datasheet link

OPN	SP Number	Package
AIMDQ75R020M1HXUMA1	SP005596188	PG-HDSOP-22
AIMDQ75R027M1HXUMA1	SP005596185	PG-HDSOP-22
AIMDQ75R060M1HXUMA1	SP005596182	PG-HDSOP-22
AIMDQ75R090M1HXUMA1	SP005573112	PG-HDSOP-22
AIMBG75R020M1HXTMA1	SP005582420	PG-TO263-7
AIMBG75R027M1HXTMA1	SP005596202	PG-TO263-7
AIMBG75R060M1HXTMA1	SP005596199	PG-TO263-7
AIMBG75R090M1HXTMA1	SP005582402	PG-TO263-7
IMDQ75R020M1HXUMA1	SP005935771	PG-HDSOP-22
IMDQ75R027M1HXUMA1	SP005935767	PG-HDSOP-22
IMDQ75R060M1HXUMA1	SP005935763	PG-HDSOP-22
IMDQ75R090M1HXUMA1	SP005588268	PG-HDSOP-22

6500 V, 1000 A single switch IGBT module FZ1000R65KE4

IHV 6500 V, 1000 A, 190 mm single switch IGBT Module with IGBT4 Trench field stop technology is the best solution for your HVDC-VSC, traction and industry applications.

Features

- Low $V_{(CEsat)}$
- AlSiC base plate
- Storage temperature down to –55°C
- Package with CTI > 600

Benefits

- Enabling compact inverter designs
- Low power losses
- Standardized housing

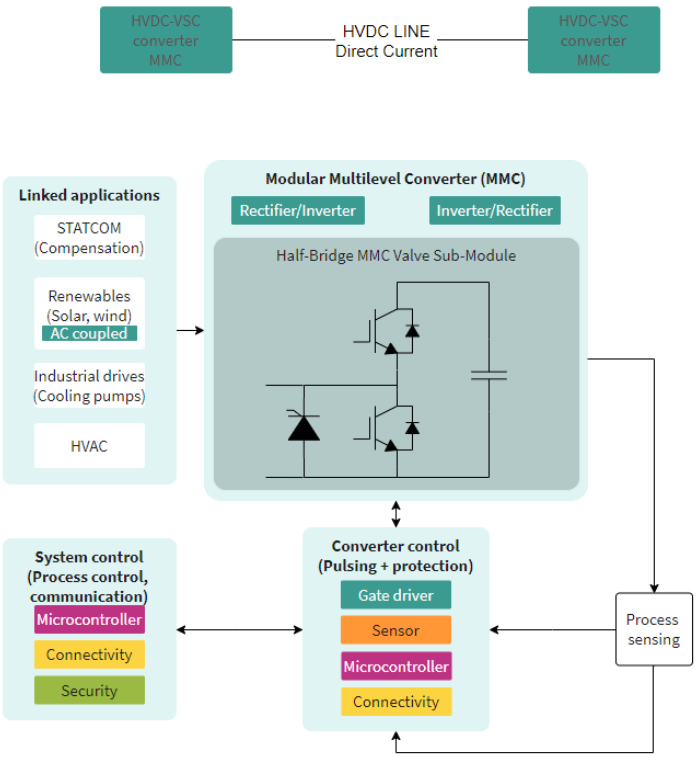
Target applications

- HVDC-VSC
- Traction
- MVD

Competitive advantage

- High performance
- Robust and reliable
- Low power losses

Block diagram



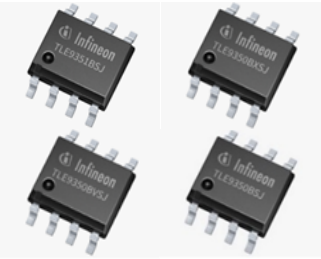
Product collaterals / Online support

Product page

Product overview incl. datasheet link

OPN	SP Number	Package
FZ1000R65KE4NPSA1	SP005897234	A-IHV190-461

CAN FD 5MB Family TLE935*B*



The new CAN FD 5MB TLE935*B* transceiver family is used in HS CAN systems for automotive applications as well as for industrial applications. It is designed to fulfill the requirements of ISO 11898-2:2016 physical layer specification as well as SAE J1939 and SAE J2284.

Features

- Loop delay symmetry for CAN FD data frames up to 5 Mbit/s
- Very low electromagnetic emission (EME) allows the use without additional common mode choke
- Optional VIO input for voltage adaption to the microcontroller interface (3.3 V or 5 V)
- Excellent ESD robustness
- TxD timeout function
- Very low CAN bus leakage current in power-down state
- Overtemperature protection
- Power-save mode
- Green product (RoHS compliant)

Benefits

- Very low current consumption due to power safe mode and very low leakage current
- Excellent ESD robustness allowing use without external protection devices
- Excellent EMC without additional external circuitry

Target applications

- Engine control units (ECU)
- Body control modules (BCM)
- Electric power steering
- Transmission control units (TCUs)
- Chassis control modules

Competitive advantage

- High mission profile 3000h (HTOL)
- Very low power consumption thru power save mode
- Excellent ESD robustness

Product collaterals / Online support

Product family page

Product overview incl. datasheet link

OPN	SP Number	Package
TLE9351BSJXTMA1	SP005593702	PG-DSO-8
TLE9350BXSJXTMA1	SP005593704	PG-DSO-8
TLE9350BVSJXTMA1	SP005593706	PG-DSO-8
TLE9350BSJXTMA1	SP005593708	PG-DSO-8

AIROC™ CYW43022 Wi-Fi 5 + Bluetooth® 5.4 combo – an ultra-low-power solution for IoT applications needing long battery life

AIROC™ CYW43022 1x1 dual-band (2.4/5 GHz) Wi-Fi 5 (802.11ac) + Bluetooth® 5.4 is an ultra-low-power connectivity device designed to address IoT designs needing minimal power consumption and compact size. Applications such as wearables, IP cameras, and smart door locks are ideally suited for the CYW43022 with its low transmit / receive power and optimized deep sleep mode. An embedded Bluetooth® stack and Wi-Fi networking offloads allow CYW43022 to save system-level power by handling Bluetooth® and Wi-Fi connectivity activity without the involvement of a host processor.

Features

- Wi-Fi 5 (802.11ac) – 1 x 1 dual-band (2.4/5 GHz)
- 20-MHz channels, up to 78-Mbps PHY data rate
- Integrated internal PA and LNA switch support a single antenna shared between Wi-Fi and Bluetooth®
- Network offloads for low-power host offload
- Ultra-low-power deep sleep
- Class 1 (100 m) and Class 2 (10 m) operation, +20 dBm Tx power
- Bluetooth® 5.4, supports BDR (1 Mbps), EDR (2/3 Mbps), and Bluetooth® LE
- Embedded BT / BLE stack for low-power host offload

Benefits

- Ultra-low-power saving features to maximize battery life
- Dual-band (2.4/5 GHz) helps manage congestion – +20 dBm Bluetooth® transmit power for applications with limited antennas
- AIROC™ Bluetooth® Stack and example code to shorten BT development cycle
- Reduction in development time with Wi-Fi software enablement for RTOS, Linux, and Android designs with multiple hosts supported
- Shorten time-to-market with globally certified module partners

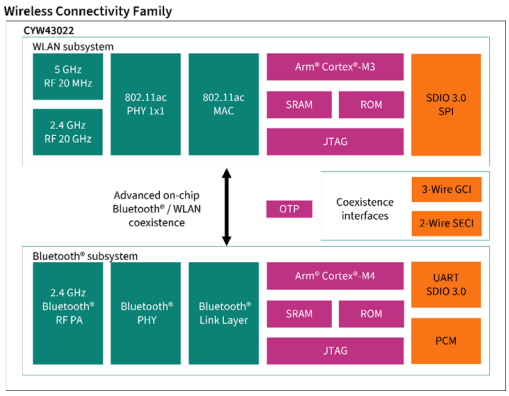
Target applications

- Battery powered applications including
  - Smart home: IP cameras, smart doorbells, smart door locks, smart thermostat
  - Smart medical / healthcare: blood pressure monitors, portable medical monitors
  - Wearables: smart watches, fitness trackers, AR glasses

Competitive advantage

- Ultra-low-power
- Enhanced features (range, network robustness, power saving on chip and system)
- Best-in-class RF performance
- Multi-layer security architecture
- Strong design expertise to make customized/flexible FW/SW
- Open source SW and tool support (FMAC)
- Support BT AIROC™ stack + example code
- Ready for Linux, Android, and capable of RTOS OS

Block diagram



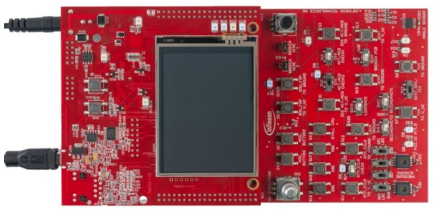
Product collaterals / Online support

Product page

Product overview incl. user manual link

Infineon Base Part	Module Partner Part Number	Infineon SP Number	Module Partner MOQ	Module Partner
CYW43022CUBT	LBEE5WV2GF-924	SP005879757	2000	Murata Manufacturing Co., Ltd.
CYW43022CUBT	AW-AM617	SP005879757	2000	Azurewave
CYW43022CUBT	WM-BAC-CYW-22	SP005879757	2000	USI

Application kit APPKIT_A2G_SAFETY



The main intention of the AURIX™ Application kit – TC3xx Safety is to provide implementation hints and code example to enable the worldwide community to use and understand the functional safety aspects AURIX™ microcontroller. The kit demonstrates the implementation of various safety mechanism (SM) and other diagnostics functionalities. The real time data is shown on TFT display and ASCLIN shell interface and the fault can be injected with touch screen and buttons / switches available on the board. The AURIX™ application kit TC3xx Safety consists of AURIX™ TC397 application kit TFT (KIT_A2G_TC397_5V_TFT) connected to the add-on shield board called evaluation board AURIX™ TC3xx Safety (EVABOARD_A2G_SAFETY), power supply, USB cable, small magnet, quick start guide and pre-flashed software.

Features

- Hardware:
  - AURIX™ TC397 application kit TFTKIT_A2G_TC397_5V_TFT)
  - TLF35584 PMIC
  - TFT touch display
  - Status LEDs
  - Evaluation board AURIX™ TC3xx Safety (EVABOARD_A2G_SAFETY)
  - TLE5012BD E9200 magnetic sensor
  - Temperature sensor
  - KP256 pressure sensor
  - Encoder for generating PWM
  - Potentiometer for broken wire detection simulation
  - Buttons to inject fault in the system
  - Switches to change connection to various pins of microcontroller
  - Low power status LEDs
  - Jumper to break the line on PCB
- Software:
  - AURIX™ development studio based Well structure project
  - Boot and startup procedure including all safety mechanism involved
  - Full SMU driver implementation including SMU core, SMU standby, fault signaling protocol (FSP), Emergency Stop (ES) and Recovery Timer (RT)
  - Implementation of different safety mechanisms for safe application
  - Fault injection for testing of various safety mechanism and accordingly alarm generation
  - TFT touch screen driver
  - TLF35584 PMIC driver
  - Commands and monitoring via TFT touch screen
  - ASCLIN Shell Interface for terminal view
  - STM used for basic task scheduling

Benefits

- Everything you need to start developing in one package, enabling fast prototyping and minimizing R&D resources
- Access to AURIX™ TC3xx family features, including high computing performance of AURIX™ TC397, multi core architecture, flexibility, scalability, integrated safety and security support
- Application notes for hardware and software available

Target applications

- Chassis, safety and ADAS
- Body electronics and lighting
- Electric drivetrain

Product collaterals / Online support

Board page

Product overview incl. user manual link

OPN	SP Number
APPKITA2GSAFETYTOBO1	SP005987751

Evaluation kit EVAL_PMG1_S1_DRP

EVAL_PMG1_S1_DRP is an evaluation kit for EZ-PD™ PMG1-S1 USB power delivery (PD) microcontroller (MCU). EZ-PD™ PMG1-S1 is targeted for applications that are powered by USB-C PD port and need a microcontroller for system and power management. The kit is used to sink up to 100 W and source up to 27 W. The kit is supported with EZ-PD™ PMG1-S1 SDK on ModusToolbox™.

Features

- Supports USB-C PD 3.1 spec up to 100 W
- ARM® Cortex®-M0 MCU
- 128 KB Flash, 12 KB SRAM
- High voltage protection circuits

Benefits

- Fully programmable and flexible MCU
- Allows easy application development
- SDK on ModusToolbox™ and PMG1 kits
- Huge USB-C PD stack for interoperability

Target applications

- Industrial and consumer BMS
- Home entertainment
- Home appliances
- Personal care

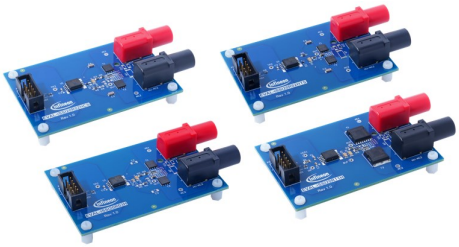
Product collaterals / Online support

Board page

Product overview incl. user manual link

OPN	SP Number
EVALPMG1S1DRPTOBO1	SP006007396

Evaluation boards for Infineon 8-pin Solid State Isolators



The advanced Infineon solid-state isolators provide powerful energy transmission over a galvanic isolation barrier to drive the gates of MOS-controlled power transistors, such as CoolMOS™, OptiMOS™ or TRENCHSTOP™ IGBT. On the output, a dedicated voltage supply is not required to drive the power transistor's gate. The Infineon SSI family offers advanced control functions such as fast turn-on/-off, over-current protection and over-temperature protection to easily and safely build up solid-state relays for various applications.

Features

- EVAL-iSSI20R02HCS
  - iSSI20R02H+2 OptiMOS™ ISC015N06NM5LF
  - Ultra-fast overcurrent detection (20A)
  - Dynamic Miller clamping
- EVAL-iSSI20R02HTS
  - iSSI20R02H+2 OptiMOS™ ISC035N10NM5LF
  - Over-temperature protection with PTC resistor
  - Dynamic Miller clamping
- EVAL-iSSI20R03H
  - iSSI20R03H+2 OptiMOS™ ISC035N10NM5LF
  - Ultra-fast overcurrent detection (20A)
  - Over-temperature protection with PTC resistor
- EVAL-iSSI20R11H
  - iSSI20R11H and two CoolMOS™ IPT60R065S7
  - Ultra-fast OCP at 10A
  - Over-temperature protection with PTC resistor
- All
  - AC switch configuration
  - Fast turn-on
  - Fast turn-off after overcurrent / overtemperature event

Benefits

- Fast iSSI evaluation and design for 8-pin Solid State Isolators

Target applications

- Solid-state relay AC and DC applications
- Electro-mechanical relay replacements
- Programmable logic controllers
- Industrial automation, and controls
- Smart building and home automation systems (thermostat, lighting, heating control)
- Instrumentation equipment
- Battery management systems
- Power distribution cabinets

Competitive advantage

- Total cost of ownership versus electromechanical relays (EMRs)
- BOM reduction in volume, size, component count and cost
- System and switch level protection

Product collaterals / Online support

Board page EVAL-ISSI20R02HCS

Board page EVAL-ISSI20R02HTS

Board page EVAL-ISSI20R03H

Board page EVAL-ISSI20R11H

Product overview incl. user manual link

OPN	SP Number
EVALISSI20R02HCSTOBO1	SP006046638
EVALISSI20R02HTSTOBO1	SP006046641
EVALISSI20R03HTOBO1	SP006046644
EVALISSI20R11HTOBO1	SP006046647

PSoC™ Automotive CY3290-CYAT8168X Multitouch 6XL evaluation kit

The PSoC™ Automotive CY3290-CYAT8168X Multitouch Evaluation Kit (EVK) is based on the Gen6 XL family of capacitive multi-touch all-points touchscreen controllers for automotive infotainment applications. The PSoC™ Automotive CYAT8168X Multitouch is able to support ten-finger tracking on touchscreens up to 15 inches and is optimized for performance: high signal-to-noise ratio (SNR), fast refresh rates, superior EMC performance and also support of advanced features like gestures, glove touch and water-proofing.

The automotive CYAT8168X EVK is a powerful platform for demonstrating the chip's capabilities and includes all the hardware and software needed to configure, optimize, and evaluate touchscreen solutions.

Features

- Automotive CY3290-CYAT8168X EVK contents:
  - PSoC™ Automotive Multitouch evaluation kit with 10.1" diagonal ITO panel enclosed in plastic casing
  - USB drive with documentation, PSoC™ Automotive Multitouch Host Emulator software, Quick Start Guide, and design files
  - Quick Start Guide (hardcopy)
- Software:
  - CY3290-CYAT8168X touchscreen controlled EVK
  - PSoC™ Multitouch Touch Tuning Host Emulator
  - PSoC™ Multitouch Manufacturing Test Kit

Target applications

- Infotainment

Product collaterals / Online support

Board page

Product overview incl. user manual link

OPN	SP Number
CY3290-CYAT8168X	SP005669707

TRAVEO™ T2G Cluster 4M Lite Kit

The TRAVEO™ T2G Cluster 4M Lite Kit is a low-cost evaluation board for the TRAVEO™ T2G CYT3DL device, featuring an on-board Miniprog4 for programming and debugging. The CYUSB3014-BZXC component converts the RGB display signals into USB packets, allowing the resulting RGB frames to be viewed by running a media player application on a PC.

Features

- Pmod connector to support external RMII Ethernet Phy (DP83848)
- On-board Miniprog4 for program and debug functionalities
- On-board CYUSB3014-BZXC to stream RGB display signals to PC through USB packets
- High-speed Serial Memory interface using flash (S26HL) and RAM (S27KL)
- Multiple interfaces like Arduino, Mikrobus, 2x Shield_2_Go and a raspberry pi are supported
- LVDS connector to support G070Y2 FPD display
- LVDS connector to support OV5640 MIPI camera
- Potentiometer, LEDs and buttons to test basic functionalities.

Benefits

- A low cost and quick solution to rapidly develop an instrument cluster prototype using TRAVEO™ T2G CYT3DL device
- Display output can be viewed in PC, thereby removing the need of physical displays

Target applications

- Instrument cluster
- Cockpit
- Two-wheelers
- Commercial, construction and agricultural vehicles (CAV)

Product collaterals / Online support

Board page

Product overview incl. user manual link

OPN	SP Number
KITT2GC-2D-4MLITE	SP005922725